

SLIM SMD INDUCTOR
-- ETPRH2D11 SERIES



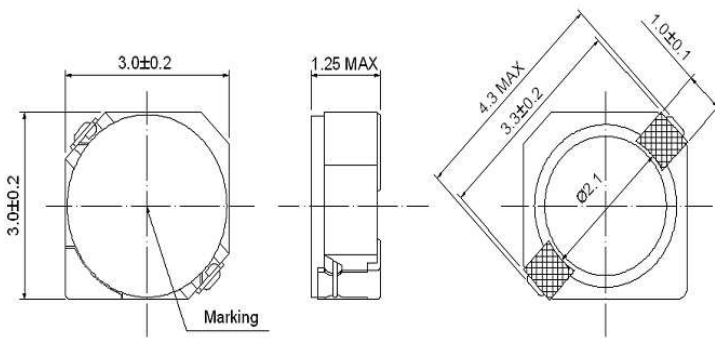
● FEATURE

1. Low profile and small size (Height: 1.25mm Max)
2. Low DC resistance
3. Magnetic Shielding type

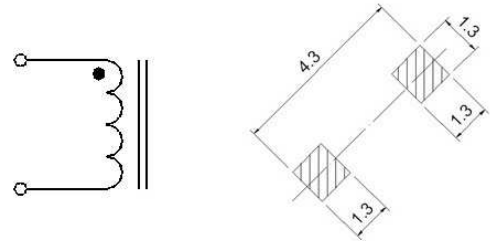
● Applications

1. LCD panels, Digital camera
2. PDA and others portable

● Shape and Dimension



● Schematics and Land Patterns(mm)



● Specification

| Part Number | L(uH) | DCR(ΩMax) | IDC(A)(Max) |
|----------------|---------|-----------|-------------|
| ETPRH2D11-2R2N | 2.2±30% | 0.094 | 0.78 |
| ETPRH2D11-3R3N | 3.3±30% | 0.120 | 0.60 |
| ETPRH2D11-4R7N | 4.7±30% | 0.162 | 0.50 |
| ETPRH2D11-6R8N | 6.8±30% | 0.319 | 0.44 |
| ETPRH2D11-100N | 10±30% | 0.377 | 0.35 |
| ETPRH2D11-220N | 22±30% | 0.800 | 0.25 |
| ETPRH2D11-470N | 47±30% | 1.950 | 0.16 |

Note1. Measurement frequency of Inductance value : at 100KHz, 1V

Note2. Measurement ambient temperature of L, DCR and IDC : at 25°C

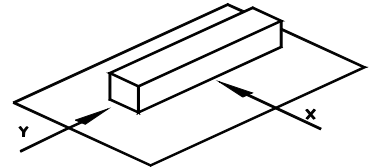
Note3. The rated current indicates the current when the inductance decreases to 65% over of it's nominal value or D.C. current when the temperature rising Δt=30°C lower, whichever is lower

Note4. Inductance tolerance: N: ±30%

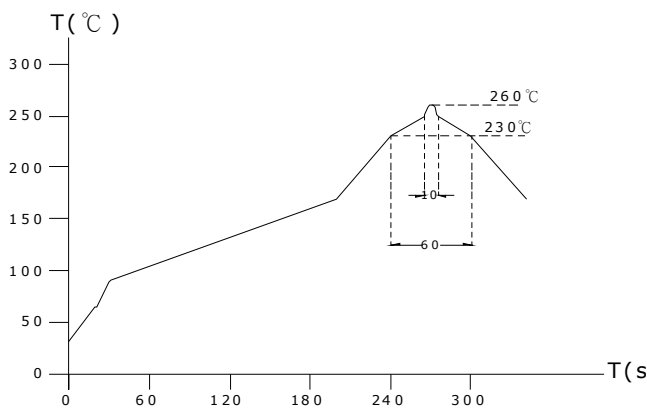


GENERAL CHARACTERISTICS

1. Operating temperature range: -40 TO + 105°C (Includes temperature when the coil is heated)
2. External appearance: On visual inspection, the coil has no external defects.
3. Terminal strength: After soldering. Between copper plate and terminals of coil. Push in two directions of X.Y withstanding at below conditions.
Terminal should not peel off. (refer to figure at right) 5. 0N 60 sec.
4. Insulating resistance: Over 100MΩ at 100V D.C. between coil and core.
5. Dielectric strength: No dielectric breakdown at 100V D.C. for 1 minute between coil and core.
6. Temperature characteristics: Inductance coefficient $(0\sim 2,000)\times 10^{-6}/^{\circ}\text{C}$ (-25~+80°C).
7. Humidity characteristics(Moisture Resistance): Inductance deviation within $\pm 5\%$, after 96 hours in 90~95% relative humidity at $40 \pm 2^{\circ}\text{C}$ and 1 hour drying under normal condition.
8. Vibration resistance: Inductance deviation within $\pm 5\%$, after vibration for 1 hour. In each of three orientations at sweep vibration (10~55~10 Hz) with 1.5mm P-P amplitudes.
9. Shock resistance: Inductance deviation within $\pm 5\%$, after being dropped once with 981m/s² (100G) shock attitude upon a rubber block method shock testing machine, in three different orientations.
10. Resistance to Soldering Heat: 260°C, 10 seconds(See attached recommend reflow)
11. Storage environment: Storage condition: Temperature Range: 10°C ~ 35°C (Generally: 21°C ~ 31°C) , Humidity Range: 50% ~ 80% RH (Generally: 65% ~ 75%) ; Transportation condition: Temperature Range: -35°C ~ 85°C , Humidity Range: 50% ~ 95% RH
12. Use components within 6 months. If 6 months or more have elapsed, check solderability before use.
13. Reflow profile recommend:



Lead-free heat endurance test



Lead-free the recommended reflow condition

